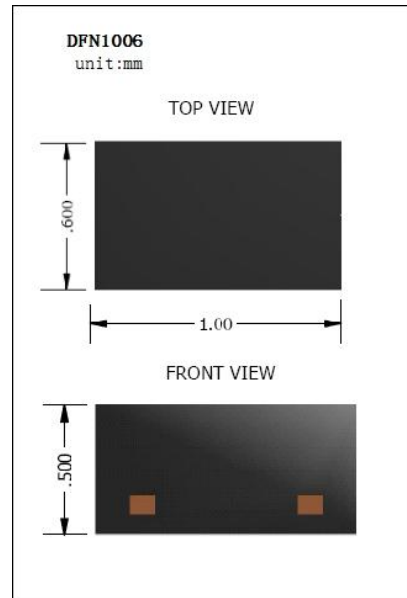
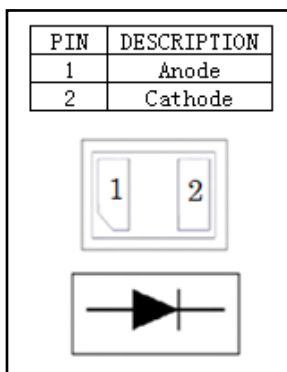


## FEATURES

- ◇ Planar Die construction
- ◇ 250mW Power Dissipation
- ◇ Zener Voltages from 2.4V–75V
- ◇ RoHS compliant / Green EMC



## MAXIMUM RATINGS (T<sub>a</sub> = 25 °C)

Symbol	Parameter	Value	Units
V <sub>F</sub>	Maximum Forward Voltage @ I <sub>F</sub> =10mA	0.9	V
P <sub>(AV)</sub>	Power Dissipation	250	mW
T <sub>J</sub> , T <sub>stg</sub>	Operating And Storage Temperature	-55 to 150	°C
I <sub>FSM</sub>	Peak Forward Surge Current	2.0	A
T <sub>stg</sub>	Storage Temperature Range	-55 to 150	°C
R <sub>j</sub>	Thermal Resistance Junction to Ambient	417	°C/W

## ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C unless otherwise noted)

Type	Device	V <sub>Z</sub> (V) *1			I <sub>ZT</sub>	Z <sub>ZT</sub> @I <sub>ZT</sub>	Z <sub>ZK</sub> @I <sub>ZK</sub>	I <sub>ZK</sub>	I <sub>R</sub>	V <sub>R</sub>
		Nom(V)	Min(V)	Max(V)						
BZX884B2V4	A1	2.4	2.35	2.45	5	100	400	1	50	1
BZX884B2V7	A2	2.7	2.65	2.75	5	100	450	1	20	1
BZX884B3V0	A3	3	2.94	3.06	5	95	500	1	10	1
BZX884B3V3	A4	3.3	3.23	3.37	5	95	500	1	5	1
BZX884B3V6	A5	3.6	3.53	3.67	5	90	500	1	5	1
BZX884B3V9	A6	3.9	3.82	3.98	5	90	500	1	3	1
BZX884B4V3	A7	4.3	4.21	4.39	5	90	600	1	3	1



# BZX884B2V4 THRU BZX884B75

Zener Diode



Type	Device	V <sub>Z</sub> (V) * <sup>1</sup>			I <sub>ZT</sub>	Z <sub>ZT</sub> @I <sub>ZT</sub>	Z <sub>ZK</sub> @I <sub>ZK</sub>	I <sub>ZK</sub>	I <sub>R</sub>	V <sub>R</sub>
Number	Marking	Nom(V)	Min(V)	Max(V)	mA	Ω		(mA)	(uA)	(V)
BZX884B4V7	A8	4.7	4.61	4.79	5	80	500	1	3	2
BZX884B5V1	A9	5.1	5	5.2	5	60	480	1	2	2
BZX884B5V6	AA	5.6	5.49	5.71	5	40	400	1	1	2
BZX884B6V2	AB	6.2	6.08	6.32	5	10	150	1	3	4
BZX884B6V8	AC	6.8	6.66	6.94	5	15	80	1	2	4
BZX884B7V5	AD	7.5	7.35	7.65	5	15	80	1	1	5
BZX884B8V2	AE	8.2	8.04	8.36	5	15	80	1	0.7	5
BZX884B9V1	AF	9.1	8.92	9.28	5	15	100	1	0.5	6
BZX884B10	AG	10	9.8	10.2	5	20	150	1	0.2	7
BZX884B11	AH	11	10.78	11.22	5	20	150	1	0.1	8
BZX884B12	AJ	12	11.76	12.24	5	25	150	1	0.1	8
BZX884B13	AK	13	12.74	13.26	5	30	170	1	0.1	8
BZX884B15	AL	15	14.7	15.3	5	30	200	1	0.05	10.5
BZX884B16	C1	16	15.68	16.32	5	40	200	1	0.05	11.2
BZX884B18	C2	18	17.64	18.36	5	45	225	1	0.05	12.6
BZX884B20	C3	20	19.6	20.4	5	55	225	1	0.05	14
BZX884B22	C4	22	21.56	22.44	5	55	250	1	0.05	15.4
BZX884B24	C5	24	23.52	24.48	5	70	250	1	0.05	16.8
BZX884B27	C6	27	26.46	27.54	2	80	300	0.5	0.05	18.9
BZX884B30	C7	30	29.4	30.6	2	80	300	0.5	0.05	21
BZX884B33	C8	33	32.34	33.66	2	80	325	0.5	0.05	23.1
BZX884B36	C9	36	35.28	36.72	2	90	350	0.5	0.05	25.2
BZX884B39	CA	39	38.22	39.78	2	130	350	0.5	0.05	27.3
BZX884B43	CB	43	42.14	43.86	2	150	375	0.5	0.05	30.1
BZX884B47	CC	47	45.83	48.17	2	170	375	0.5	0.05	32.9
BZX884B51	CD	51	49.73	52.27	2	180	400	0.5	0.05	35.7
BZX884B56	CE	56	54.6	57.4	2	200	425	0.5	0.05	39.2
BZX884B62	CF	62	60.45	63.55	2	215	450	0.5	0.05	43.4
BZX884B68	CG	68	66.3	69.7	2	240	475	0.5	0.05	47.6
BZX884B75	CH	75	73.13	76.87	2	255	500	0.5	0.05	52.5

\*1 Pulse width = 10 ms

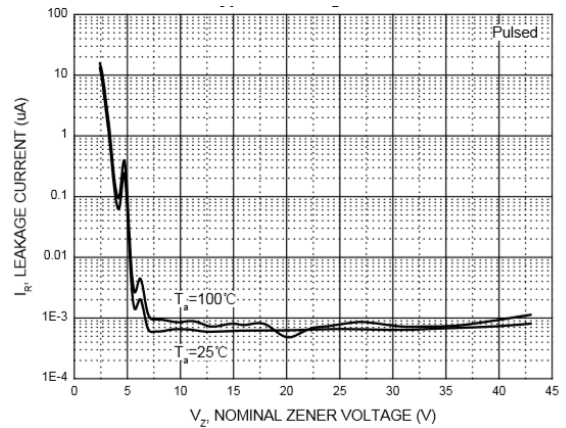
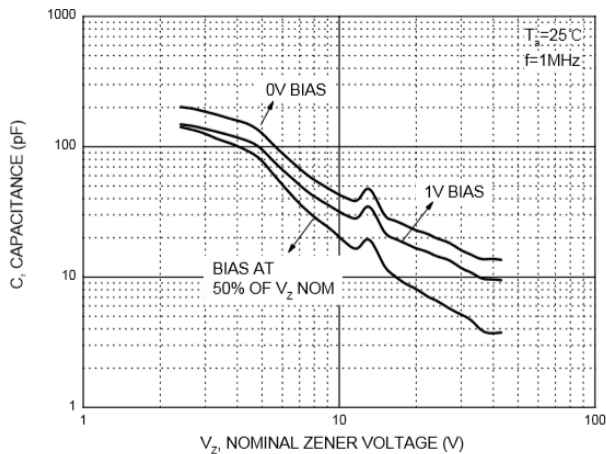
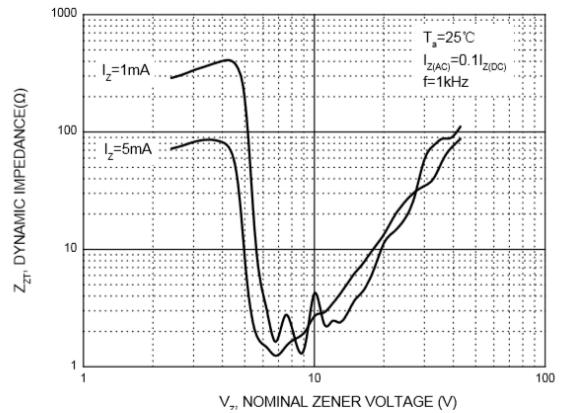
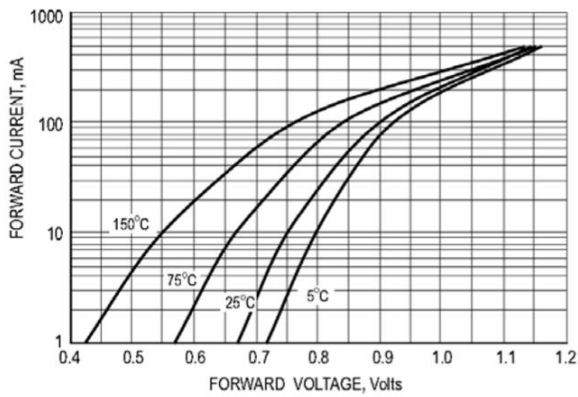
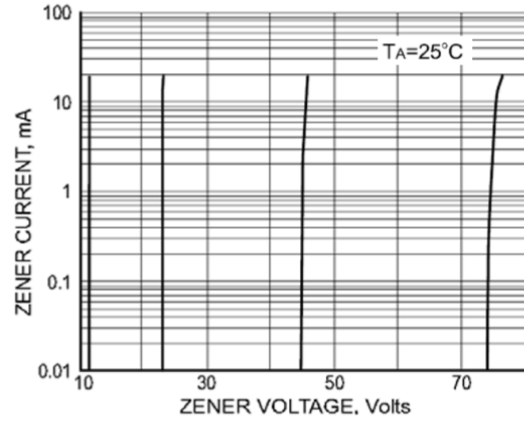
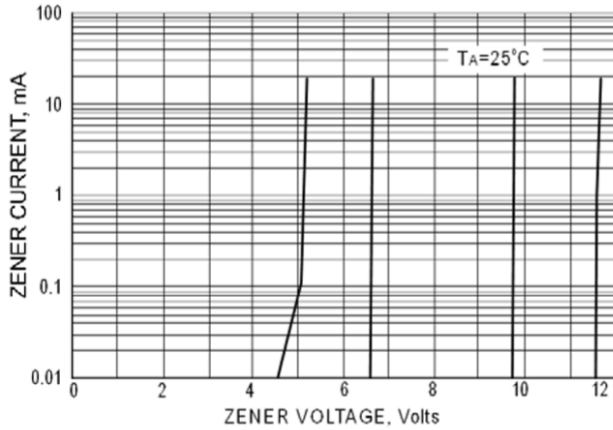


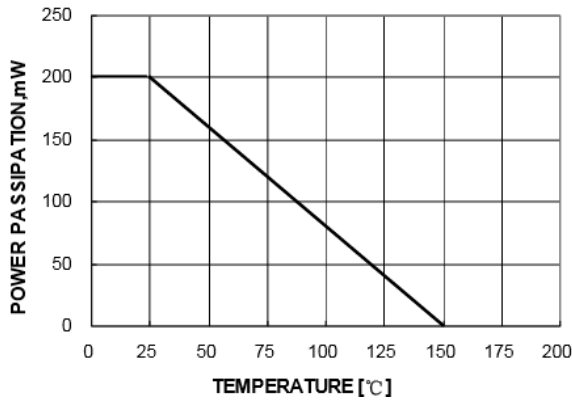
# BZX884B2V4 THRU BZX884B75

Zener Diode



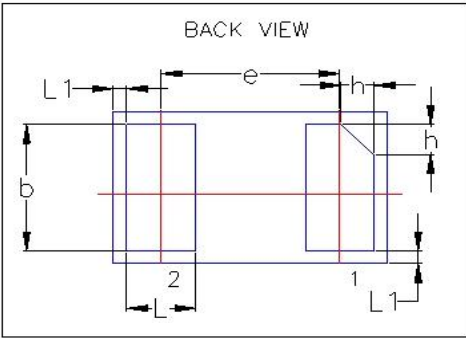
## Typical Characteristics



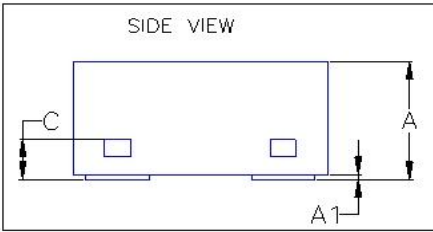


## PACKAGE DIMENSIONS

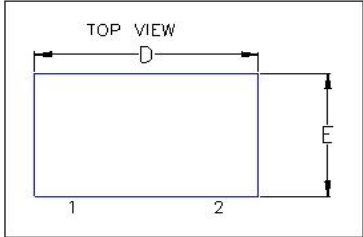
**Package outline : DFN1006**



BACK VIEW



SIDE VIEW



TOP VIEW

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.45	0.50	0.55
A1	0.00	0.02	0.05
b	0.45	0.50	0.55
C	0.12	0.15	0.18
D	0.95	1.00	1.05
e	0.65BSC		
E	0.55	0.60	0.65
L	0.20	0.25	0.30
L1	0.05 REF.		
h	0.07	0.12	0.17

1. Lead plating: Pb free solder  
 2. Lead thickness includes solder plating  
 3. Lead frame: Copper A194  
 4. Other Tolerance:  $\pm 0.05$   
 6. Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions  
 5. Unit: mm

Device	Package	Shipping
BZX884B2V4-BZX884B75	DFN1006	10000/Tape&Reel